



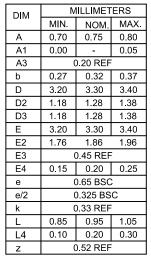


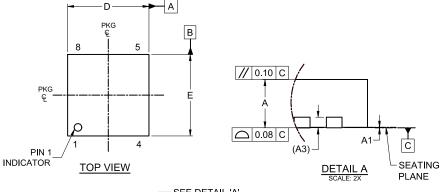
PQFN8 3.3X3.3, 0.65PCASE 483BP ISSUE A

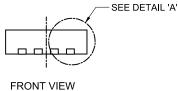
DATE 21 MAY 2021

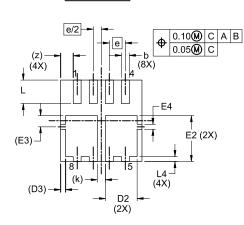
NOTES:

- A. PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002CONTROLLING
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

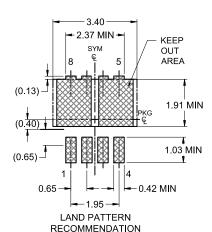








BOTTOM VIEW



*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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